Serial NO. 09/903,160 Atty. Docket No. MIO 0062 PA

## **APPENDIX**

KILLWORTH ET AL

## In the Claims

Please cancel claims 30-37.

- 39. (New) A method for forming a capacitor comprising: providing a non-oxide electrode selected from the group consisting of TiN, TaN, WN, and W, in a deposition chamber oxidizing an upper surface of said non-oxide electrode in an atmosphere containing a gas plasma generated from a gas selected from the group consisting of O<sub>2</sub>, O<sub>3</sub>, H<sub>2</sub>O, and N<sub>2</sub>O, in the same deposition chamber depositing a high dielectric constant oxide dielectric material selected from the group consisting of Al<sub>2</sub>O<sub>3</sub>, Ta<sub>2</sub>O<sub>5</sub> and Ba<sub>x</sub>Sr<sub>(1-x)</sub>TiO<sub>3</sub> on the oxidized surface of said non-oxide electrode, and depositing an upper layer electrode on said high dielectric constant oxide dielectric material.
- 40. (New) A method for forming a capacitor comprising: providing a non-oxide electrode, in a deposition chamber oxidizing an upper surface of said non-oxide electrode in an atmosphere containing a gas plasma generated from a gas selected from the group consisting of O<sub>2</sub>, O<sub>3</sub>, H<sub>2</sub>O, and N<sub>2</sub>O, in the same deposition chamber depositing a high dielectric constant dielectric material on the oxidized surface of said non-oxide electrode, and depositing an upper layer electrode on said high dielectric constant oxide dielectric material.
- 41. (New) A method for forming a capacitor comprising: providing a non-oxide electrode selected from the group consisting of TiN, TaN, WN, and W, in a deposition chamber oxidizing an upper surface of said non-oxide electrode, in the same deposition chamber depositing a high dielectric constant oxide dielectric material on the oxidized surface of said non-oxide electrode, and depositing an upper layer electrode on said high dielectric constant oxide dielectric material.